ABSTRACT OF THE DISCLOSURE

A semiconductor chip and a fabrication method thereof are disclosed. In the fabrication method, isotropic etching and anisotropic etching are performed on a cutting portion of a semiconductor wafer to form grooves in the semiconductor wafer. Through these grooves, the semiconductor wafer can be diced with no use of any dicing blade. In addition, it is possible to form semiconductor chips whose edges and corners are rounded off. According to the fabrication method, fabrication time can be shorten. In addition, it is possible to improve integration and yield of semiconductor chip formation.